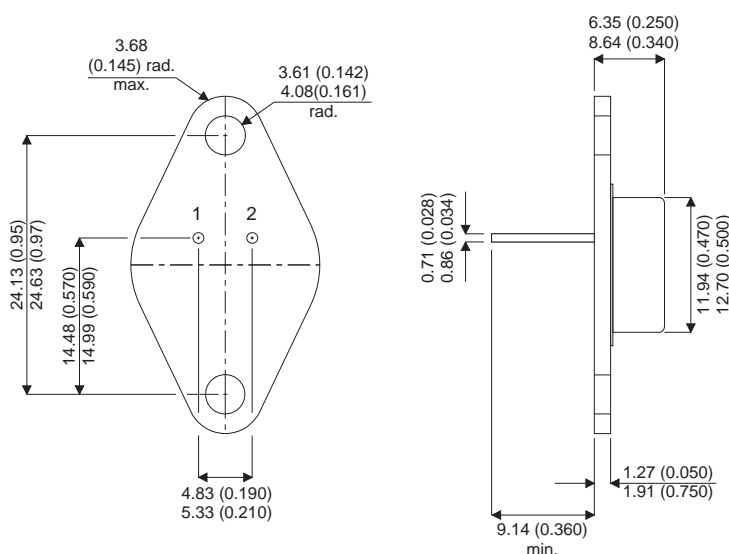


MECHANICAL DATA

Dimensions in mm (inches)



TO-66 METAL PACKAGE (TO213AA)

Underside View

Pin 1 = Gate Pin 2 = Source Case = Drain

**N-CHANNEL
POWER MOSFET
FOR HI-REL
APPLICATIONS**

V_{DSS} **200V**
 $I_{D(cont)}$ **13A**
 $R_{DS(on)}$ **0.18Ω**

FEATURES

- HERMETICALLY SEALED TO-66 METAL PACKAGE
- SIMPLE DRIVE REQUIREMENTS
- SCREENING OPTIONS AVAILABLE

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

V_{GS}	Gate – Source Voltage	±20V
I_D	Continuous Drain Current @ $T_{case} = 25^{\circ}C$	13A
I_D	Continuous Drain Current @ $T_{case} = 100^{\circ}C$	8A
I_{DM}	Pulsed Drain Current	50A
P_D	Power Dissipation @ $T_{case} = 25^{\circ}C$	70W
	Linear Derating Factor	0.56W/°C
T_J, T_{stg}	Operating and Storage Temperature Range	-55 to 150°C
$R_{\theta JC}$	Thermal Resistance Junction to Case	1.8°C/W max.
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	50°C/W max.

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ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise stated)

Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
STATIC ELECTRICAL RATINGS						
BV_{DSS}	Drain – Source Breakdown Voltage	$V_{GS} = 0$	$I_D = 250\mu\text{A}$	200	V	
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Temperature Coefficient of Breakdown Voltage	Reference to 25°C $I_D = 1\text{mA}$		1.42	$\text{V}/^\circ\text{C}$	
$R_{DS(on)}$	Static Drain – Source On–State Resistance	$V_{GS} = 10\text{V}$	$I_D = 7\text{A}^*$	0.14	0.18	Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$	$I_D = 250\mu\text{A}$	2	4	V
g_{fs}	Forward Transconductance	$V_{DS} \geq I_D \times R_{DS(on)}$ $I_D = 7\text{A}^*$		6	9	$\text{S}(\bar{v})$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0$	$V_{DS} = 0.8BV_{DSS}$ $T_J = 125^\circ\text{C}$		250 1000	μA
I_{GSS}	Forward Gate – Source Leakage	$V_{GS} = 20\text{V}$			100	nA
I_{GSS}	Reverse Gate – Source Leakage	$V_{GS} = -20\text{V}$			-100	
DYNAMIC CHARACTERISTICS						
C_{iss}	Input Capacitance	$V_{GS} = 0$		1275		pF
C_{oss}	Output Capacitance	$V_{DS} = 25\text{V}$		500		
C_{rss}	Reverse Transfer Capacitance	$f = 1\text{MHz}$		160		
Q_g	Total Gate Charge	$V_{GS} = 10\text{V}$ $I_D = 16\text{A}$		43	60	nC
Q_{gs}	Gate – Source Charge	$V_{DS} = 0.8BV_{DSS}$		16		
Q_{gd}	Gate – Drain (“Miller”) Charge			27		
$t_{d(on)}$	Turn–On Delay Time	$V_{DD} = 75\text{V}$		16	30	ns
t_r	Rise Time	$I_D = 7\text{A}$		27	60	
$t_{d(off)}$	Turn–Off Delay Time	$Z_0 = 4.7\Omega$		40	80	
t_f	Fall Time			31	60	
SOURCE – DRAIN DIODE CHARACTERISTICS						
I_S	Continuous Source Current				13	A
I_{SM}	Pulse Source Current				50	
V_{SD}	Diode Forward Voltage	$I_S = 13\text{A}$	$T_J = 25^\circ\text{C}$		2	V
t_{rr}	Reverse Recovery Time	$I_F = 13\text{A}$	$T_J = 25^\circ\text{C}$		650	ns
Q_{rr}	Reverse Recovery Charge	$d_i / d_t \leq 100\text{A}/\mu\text{s}$ $V_{DD} \leq 50\text{V}$			4.1	μC
PACKAGE CHARACTERISTICS						
L_D	Internal Drain Inductance	(from 6mm down drain lead pad to centre of die)		5.0		nH
L_S	Internal Source Inductance	(from 6mm down source lead to centre of source bond pad)		12.5		

* Pulse width $\leq 300\mu\text{s}$; Duty Cycle $\leq 2\%$

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